

L Number	Hits	Search Text	DB	Time stamp
92	25	(flexible with printed with wiring with board) same ((resin or epoxy or adhesive) with bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 15:38
93	3	(flexible with printed with wiring with board) same ((resin or epoxy) with bump with adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 15:44
94	9	((second or first or lower or upper or top or bottom) near (resin or epoxy or adhesive or coat or coating)) with bump) same (pcb or (printed adj wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 15:45
95	15	((second or first or lower or upper or top or bottom) near (resin or epoxy or adhesive or coat or coating)) with bump) same (pcb or (printed near2 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 15:49
96	131	((second or first or lower or upper or top or bottom) near (resin or epoxy or adhesive or coat or coating)) with (ball or solder or bump)) same (pcb or (printed near2 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 15:50